UL Product iQ®

Wiring, Printed - Component

COMPANY

Dongguan Xingcheng Electronic Technology Co.,Ltd
No, 2 Building, No. 25, Deshengxi Road, Gaobu Town
Dongguan, Guangdong Sheng 523282 China

E534460

Type	Cond Width Min mm	Edge mm	Cond Thk mic	SS/ DS/ DSO	Max Area Diam mm	Report date After 2022-01-01	Surface Mount Technology	Assembly Solder Process Temp °C	Process Cycles	Solder Limits °C	sec	Max Oper Temp °C	Flame Class	Meets UL796 DSR	CTI
Single layer printed wiring boards															
D(ASP1)	0.075	0.075	17	DS	76.2	Yes	Yes	260	3	-	-	130	V-0	All	*
S	0.12	0.12	17	SS	50.8	Yes	No	-	-	260	15	130	V-0	All	*
S1(ASP1)	0.12	0.12	17	SS	50.8	Yes	Yes	260	1	-	-	130	V-0	All	*

* - CTI marking is optional and may be marked on the printed wiring board.

(ASP1) - Assembly solder process evaluated to IPC-TM-650, 2.6.27 Thermal Stress Assembly Simulation

Marking: Company nameor file number and type designation. May be followed by a suffix to denote factory identification or flammability classification..

Last Updated on 2023-07-04

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Feedback

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Guide Information

Dongguan Xingcheng Electronic Technology Co.,Ltd

No, 2 Building, No. 25, Deshengxi Road, Gaobu Town , Dongguan Guangdong Sheng 523282 CN

Type dsg: D(ASP1)

Single layer printed wiring boards

Cond Width Min (mm)	Cond Width Edge (mm)	Cond Thk Min (mic)	Cond Thk Max Int (mic)	Cond Thk Max Ext (mic)	SS/ DS/ DSO	Max Area Diam (mm)	Report Date After 2022-01-01	Surface Mount Technology	Assembly Solder Process Temp(°C)	Assembly Solder Process Cycles	Solder Limits Temp (°C)	Solder Limits Time (sec)	Max Oper Temp (°C)	Flame Class	Meets UL796 DSR	CTI
0.075	0.075	17	-	102	DS	76.2	Yes	Yes	260	3	-	-	130	V-0	All	*

(ASP1) - Assembly solder process evaluated to IPC-TM-650, 2.6.27 Thermal Stress Assembly Simulation

* - CTI rating may be marked on individual boards.

Report Date: 2023-07-05

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Dongguan Xingcheng Electronic Technology Co.,Ltd

No, 2 Building, No. 25, Deshengxi Road, Gaobu Town , Dongguan Guangdong Sheng 523282 CN

Type dsg: S

Single layer printed wiring boards

Cond Width Min (mm)	Cond Width Edge (mm)	Cond Thk Min (mic)	Cond Thk Max Int (mic)	Cond Thk Max Ext (mic)	SS/ DS/ DSO	Max Area Diam (mm)	Report Date After 2022-01-01	Surface Mount Technology	Assembly Solder Process Temp(°C)	Assembly Solder Process Cycles	Solder Limits Temp (°C)	Solder Limits Time (sec)	Max Oper Temp (°C)	Flame Class	Meets UL796 DSR	CTI
0.12	0.12	17	-	102	SS	50.8	Yes	No	-	-	260	15	130	V-0	All	*

* - CTI rating may be marked on individual boards.

Report Date: 2023-07-05

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Dongguan Xingcheng Electronic Technology Co.,Ltd

No, 2 Building, No. 25, Deshengxi Road, Gaobu Town , Dongguan Guangdong Sheng 523282 CN

Type dsg: S1(ASP1)

Single layer printed wiring boards

Cond Width Min (mm)	Cond Width Edge (mm)	Cond Thk Min (mic)	Cond Thk Max Int (mic)	Cond Thk Max Ext (mic)	SS/ DS/ DSO	Max Area Diam (mm)	Report Date After 2022-01-01	Surface Mount Technology	Assembly Solder Process Temp(°C)	Assembly Solder Process Cycles	Solder Limits Temp (°C)	Solder Limits Time (sec)	Max Oper Temp (°C)	Flame Class	Meets UL796 DSR	CTI
0.12	0.12	17	-	102	SS	50.8	Yes	Yes	260	1	-	-	130	V-0	All	*

(ASP1) - Assembly solder process evaluated to IPC-TM-650, 2.6.27 Thermal Stress Assembly Simulation

* - CTI rating may be marked on individual boards.

Report Date: 2023-07-05

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